

## ABSTRACT

Disclosed is a dicing/die-bonding integrated film 10 including a dicing film 5 including a substrate film 3 and a pressure-sensitive adhesive layer 2 provided on the substrate film 3, and a bonding adhesive layer composed of a die-bonding film 1 disposed on the pressure-sensitive adhesive layer 2 of the dicing film 5. The loss tangent of the dicing film 5 at 0°C is 0.15 or less.

Fig. 3